

AGENDA - MICROPRINCE Technical Meeting*19th -20th March 2019, Dresden (Germany)*

Technical meeting 19th March – Day 1			
From	To	Topic	Speaker
13:30 – 14:00		Welcome/warm-up, agenda review Introduction of TUD	XMF, TUD
14:00 – 14:30		Overall project status	XMF
14:30 – 15:30		WP1 - Design and installation of the μTP pilot line - Status, progress, next plans - 15min discussion time	XMF, X-CEL
15:30 – 15:45		<i>Coffee Break</i>	
15:45 – 16:45		WP2 – Micro-transfer-printing for high sensitivity magnetic sensors - Status, progress, next plans - Update and plans - 15 min discussion	MLX TLO, MLX BEV
16:45– 17:45		WP3 – Micro-transfer-printing for optical sensors - Status, progress, next plans - Update and plans - 15 min discussion	X-FAB, OBJ
<i>Common Dinner (approx. 19:00 CET)</i>			

Technical meeting 20th March – Day 2			
From	To	Topic	Speaker
09:00 – 09:15		Day 2 welcome and agenda	TUD, XMF
09:15 – 10:15		WP5 – Micro-transfer-printing of LED devices - Status, progress, next plans - Update and plans - 15 min discussion	MLX DE
10:15 – 11:15		WP6 – Micro-transfer-printing for biomedical implant applications - Status, progress, next plans - Update and plans - 15 min discussion	IMEC
11:15 – 11:30		<i>Coffee Break</i>	
11:30 – 12:30		Administrative issues - Update GA/EB member list - Planning of review meeting & next f2f meeting - Summary of todos	XMF, TEC
12:30 – 13:30		<i>Lunch</i>	
13:30 – 14:30		Alignment of GaN coupon preparation - Align on Source wafer preparation for D5.5	TYN, MLX DE, X-FAB, XMF, X-CEL
14:30 – 15:30		Alignment on dummy (release) tests on WP transfer - Align for upcoming transfer to pilot line	IMEC, XMF, X-FAB
15:30 – 15:45		<i>Coffee Break</i>	
15:45 – 16:45		Discussion between ISIT and IMEC on post-processing development	ISIT, IMEC